4A, 12V Lead-Acid Battery Charger IC CN3768

General Descriptions:

The CN3768 is a PWM switch-mode battery charger controller for 12V lead-acid battery in a small package using few external components.

The CN3768 is specially designed for charging 12V lead-acid battery with trickle charge, constant current charge, over-charge and float charge mode. In over-charge and float charge mode, the regulation voltage is internally set. The constant charge current is programmable with a single sense resistor.

Deeply discharged batteries are automatically trickle charged at 17.5% of the programmed constant charge current until the cell voltage exceeds 75% of the regulation voltage in over-charge mode. The over-charge is terminated once the charging current drops to 38% of the constant charge current, then CN3768 will enter float charge mode. A new charge cycle automatically restarts if the battery voltage falls below 83.95% of the over-charge voltage in float-charge mode. CN3768 will automatically enter sleep mode when input voltage is lower than battery voltage.

Other features include undervoltage lockout and status indication, etc.

CN3768 is available in a space-saving 8-pin SOP package.

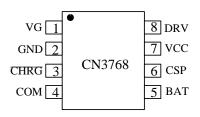
Applications:

- Mobile Loadspeaker
- Lead-Acid Battery Charger
- UPS
- Portable Industrial and Medical Equipment
- Standalone Battery Chargers

Features:

- Wide Input Voltage: 6.6V to 30V
- Complete Charger Controller for 12V Lead-Acid Battery
- Charge Current Up to 4A
- High PWM Switching Frequency: 315KHz
- Fixed Over-Charge Voltage
- Charging Current is programmed with a sense resistor
- Automatic Conditioning of Deeply Discharged Batteries
- Automatic Recharge
- Charger Status Indication
- Soft Start
- Battery Overvoltage Protection
- Operating Ambient Temperature -40° C to $+85^{\circ}$ C
- Available in 8 Pin SOP Package
- Pb-free , RoHS Compliant, and Halogen Free

Pin Assignment:



Typical Application Circuit:

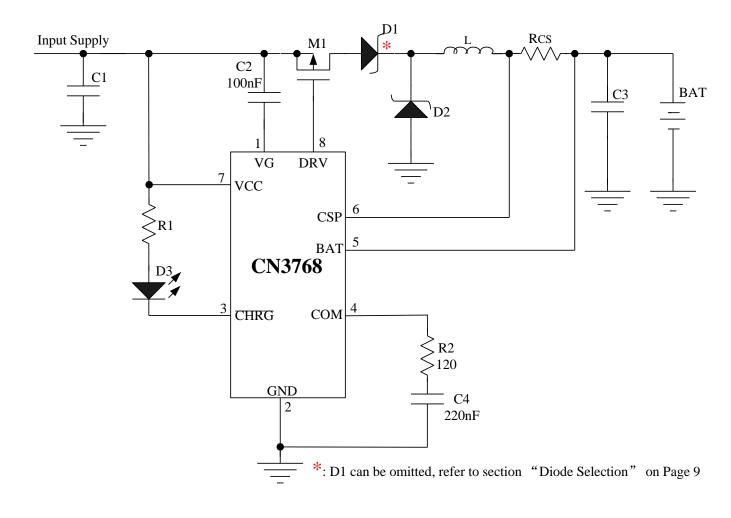


Figure 1 Typical Application Circuit

Ordering Information:

Part No.	Package Type and Packing	Operating Ambient Temperature
CN3768	SOP8, Tape and Reel, 2500/Reel	-40° C to $+85^{\circ}$ C

Pin Description:

Pin No.	Name	Descriptions			
1	VG	Internal Voltage Regulator. VG internally supplies power to gate driver, connect a 100nF capacitor between VG pin and VCC pin.			
2	GND	Ground. Negative terminal of input supply.			
	CHRG	Open-Drain Charge Status Output. This pin is pulled low by an internal switch			
3		if CN3768 is in trickle charge, constant current and over charge mode. In this pin			
		is in high impedance state.			
4	СОМ	Loop Compensation Input. Connect a 220nF capacitor in series with an 120Ω			
4		resistor from this pin to GND.			
	BAT	Negative Input for Charge Current Sensing. This pin and the CSP pin measure			
5		the voltage drop across the sense resistor R_{CS} to provide the current signals			
		required. Battery voltage is also sensed through BAT pin.			
	CSP	Positive Input for Charge Current Sensing. This pin and the BAT pin measure			
6		the voltage drop across the sense resistor R_{CS} to provide the current signals			
		required.			
7	VCC	External DC Power Supply Input. VCC is also the power supply for internal			
/		circuit. Bypass this pin with capacitors.			
8	DRV	Gate Drive Pin. Drive the gate of external P-channel MOSFET.			

Absolute Maximum Ratings

Voltage from VCC, CHRG to GND	-0.3V to $33V$
Voltage from DRV, VG to VCC	-8V to VCC $+0.3V$
Voltage from CSP, BAT to GND	-0.3V to 28V
Voltage from COM to GND	6.5V
Storage Temperature	−65°C150°C
Operating Ambient Temperature	−40°C85°C
Lead Temperature(Soldering, 10 seconds)	260°C

Stresses beyond those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to Absolute Maximum Rating Conditions for extended periods may affect device reliability.

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Electrical Characteristics:

Parameters	Symbol	Cond	litions	Min	Тур	Max	Unit	
Input Voltage Range	VCC			6.6		30	V	
Undervoltage lockout Threshold	UVLO			4	5.2	6.5	v	
Operating Current	Ivcc	$V_{BAT} > V_{OC}$ (Note1)		0.7	1.0	1.3	mA	
Current Sense Voltage	* 7	$V_{BAT} > 75\% \times V_{OC}$ (Note1)		113	120	127	mV	
$(V_{CSP} - V_{BAT})$	V _{CS}	$V_{BAT} < 75\% \times V_{OC}$ (Note1)		11	21	31		
Current into BAT Pin	I _{BAT}	V _{BAT} =12V		5	10	15	uA	
Precharge Threshold	VPRE	V _{BAT} rising			75%			
Float charge Voltage			91.57%			1		
Recharge Threshold	V _{RE}	V _{BAT} falling		83.95%		6	X 7	
	17	V _{BAT} rising, no	t in float charge	1.05	1.07	1.09	(Note1)	
Overvoltage Trip Level	Vov	V _{BAT} rising, flo	at charge mode	0.96	0.98	1.0		
	X7 1	V _{BAT} falling,no	t in float charge	1.0	1.02	1.04		
Overvoltage Clear Level	Vclr	V _{BAT} falling, fl	oat charge	0.913	0.933	0.953		
Over Charge Mode								
Regulation Voltage	V _{OC}	BAT pin, Over	Charge mode	14.58	14.8	15.02	V	
Float Charge Mode								
Regulation Voltage	V _{FLOAT}	BAT pin, Float	t Charge mode	13.35	13.55	13.75	V	
CHRG Pin								
CHRG Pin Sink Current			7	12	18	mA		
CHRG Leakage Current	I _{LK1}	V _{CHRG} =25V, F	oat mode			1	uA	
Oscillator								
Switching Frequency	fosc			255	315	375	kHZ	
Maximum Duty Cycle	Dmax				94		%	
Sleep Mode							•	
Sleep Mode Threshold (measure $VCC - V_{BAT}$)	V _{SLP}	VCC falling	V _{BAT} =12V	0.0	0.05	0.1	v	
Sleep mode Release Threshold (measure VCC-V _{BAT})	V _{SLPR}	VCC rising,	V _{BAT} =12V	0.2	0.32	0.46	v	
DRV Pin			•					
V _{DRV} High (VCC-V _{DRV})				60		mV		
V _{DRV} Low (VCC-V _{DRV})	VL	I _{DRV} =0mA		5	6.3	8	V	
Rise Time	t _r	Cload= $2nF$, 10% to 90%		30	40	65	ns	
Fall Time t _f		Cload=2nF, 90% to 10%		30	40	65	ns	

(VCC=15V, T_A =-40°C to 85°C, unless otherwise noted)

Note 1: V_{OC} is the regulation voltage at BAT pin in over-charge mode, which is 14.8V with $\pm 1.5\%$ accuracy.

Detailed Description:

The CN3768 is battery charger controller that adopts PWM step-down (buck) switching architecture, the device is specially designed for 12V lead-acid battery with trickle charge, constant current, over voltage and float charge mode. The charge current is set by an external sense resistor (R_{CS}) across the CSP and BAT pins. The battery regulation voltage V_{REG} in over charge mode is internally set at 14.8V(Typical) with $\pm 1.5\%$ accuracy. A charge cycle begins when the voltage at the VCC pin rises above the UVLO level and is greater than the battery voltage. At the beginning of the charge cycle, if the battery voltage is less than $75\% \times V_{\infty}$, the charger goes into trickle charge mode. The trickle charge current is about 17.5% of the full charge current. If the battery voltage rises above $75\% \times V_{oc}$, the charger enter constant current mode. In constant current mode, the charge current is set by the internal 0.12V reference voltage and a external resistor R_{CS}, the constant current is 0.120/Rcs. In constant current mode, CN3768 will go back to trickle charge mode if the battery voltage drops below 75% of the over charge voltage. When the battery voltage approaches the over-charge voltage, the charger goes into the over charge mode. In over charge mode, the charge current start to decrease and when the charge current drops to 38% of constant charge current, the charger goes into float-charge mode, the BAT pin voltage in float-charge mode is regulated at 13.55V(Typical). In trickle charge, constant current and over-charge mode, CHRG pin is pulled low by an internal N-channel MOSFET to indicate that the charge cycle is ongoing. During the float-charge mode, CHRG pin is in high impedance state.

In float charge mode to restart the charge cycle, just remove and reapply the input voltage. Also, a new charge cycle will begin if the battery voltage drops below the recharge threshold voltage of $83.95\% \times V_{OC}$. When the input voltage is not present, the charger goes into sleep mode.

An over-voltage comparator guards against voltage transient overshoots. In this case, P-channel MOSFET is turned off until the overvoltage condition is cleared. This feature is useful for battery load dump or sudden removal of battery.

The charging profile is shown in Figure 2.

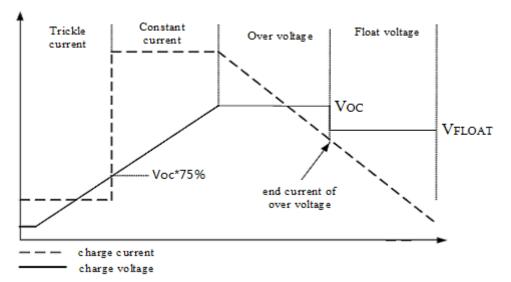


Figure 2 The Charging Profile

Application Information

Undervoltage Lockout (UVLO)

An undervoltage lockout circuit monitors the input voltage and keeps the charger off if VCC falls below 5.2V(Typical).

The Regulation Voltage in Over Voltage Mode and Float Charge Mode

The regulation voltage V_{OC} at BAT pin in over charge mode is set at 14.8V(Typical) with $\pm 1.5\%$ accuracy. In float charge mode, the regulation voltage V_{FLOAT} at BAT pin is 91.57% of that in over charge mode, which is 13.55V(Typical).

Trickle Charge Mode

At the beginning of a charge cycle, if the battery voltage is below $75\% \times V_{OC}$, the charger goes into trickle charge mode with the charge current set at about 17.5% of the constant current.

Charge Current Setting

The constant charge current, namely the charge current in constant current mode, is decided by the following formula:

ICH =
$$\frac{0.12V}{RCS}$$

Where:

 I_{CH} is the constant charge current

 R_{CS} is the resistor between the CSP pin and BAT pin

End-of-Over Charge Current

When the battery voltage approaches the over-charge voltage, the charger goes into the over charge mode. In over charge mode, the charge current start to decrease and when the charge current drops to 38% of constant charge current, the charger goes into float-charge mode.

Float Charge Mode

After the over voltage charge is terminated, the charger goes into float charge mode. In float charge mode, the battery voltage is regulated to $91.57\% \times V_{OC}$, namely 13.55V(Typical). Float charge mode can compensate for the loss of battery power due to self-discharge or external loading.

Automatic Battery Recharge

In float mode, if both the battery and the input power supply (wall adapter) are present, a new charge cycle will begin if the battery voltage drops below $83.95\% \times V_{OC}$ due to self-discharge or external loading.

A new charge cycle can also be started manually by plugging off the input supply and reapplying it.

Status Indication

The CN3768 has one open-drain status outputs: CHRG. CHRG is pulled low when the charger is in trickle charge mode, constant current mode and over charge mode.

In float mode, CHRG becomes high impedance.

When the battery is not present, the charger charges the output capacitor to the float-charge voltage.

The CHRG pin should be tied to ground if charge status indication is not needed.

The table 1 lists the indicator status and its corresponding charging status. It is supposed that red LED is connected to \overline{CHRG} pin.

CHRG pin	State Description		
Low(the red LED on)	Trickle ,constant current or over-charge mode		
	There are 3 possibilities:		
High Impedance(the red LED off)	• Float mode		
	• Input voltage is lower than UVLO level		
	• Input voltage is lower than battery voltage		

Table 1 Indication Status

Gate Drive

The CN3768's gate driver can provide high transient currents to drive the external pass transistor. The rise and fall times are typically 40ns when driving a 2000pF load, which is typical for a P-channel MOSFET with Rds(on) in the range of $50m\Omega$.

A voltage clamp is added to limit the gate drive to 8V max. below VCC. For example, if VCC is 20V, then the DRV pin output will be pulled down to 12V min. This allows low voltage P-channel MOSFETs with superior Rds(on) to be used as the pass transistor thus increasing efficiency.

Loop Compensation

In order to make sure that the current loop and the voltage loop are stable, a series-connected 220nF ceramic capacitor and 120Ω resistor from the COM pin to GND are needed(R2 and C4 in Figure 1).

Input Capacitor

Since the input capacitor(C1 in Figure 1) is assumed to absorb all input switching ripple current in the converter, it must have an adequate ripple current rating. Worst-case RMS ripple current is approximately one-half of output charge current.

In order to depress the high-frequency oscillation during P-channel MOSFET's turning on and off, it is best that the input capacitor consists of the following 3 capacitors in parallel:

- Electrolytic capacitor for low-frequency filtering
- A ceramic capacitor from 1uF to 10uF
- A high-frequency capacitor from 47nF to 1uF

Output Capacitor

The selection of output capacitor (C3 in Figure 1) is primarily determined by the ESR required to minimize ripple voltage and load step transients. it is best that the output capacitor consists of the following 2 capacitors in parallel:

- A 10uF electrolytic capacitor for low-frequency filtering
- A ceramic capacitor from 1uF to 10uF

If only ceramic capacitor can be used, cares must be taken that some ceramic capacitors exhibit large negative voltage coefficient, which may lead to high voltage at BAT pin when battery is not present. In this case, the capacitor value should be increased properly so that no damage will be done.

Inductor Selection

During P-channel MOSFET's on time, the inductor current increases, and decreases during P-channel MOSFET's off time, the inductor's ripple current increases with lower inductance and higher input voltage. Higher inductor ripple current results in higher charge current ripple and greater core losses. So the inductor's ripple current should be limited within a reasonable range.

The inductor's ripple current is given by the following formula:

Where,

f is the switching frequency 315KHz

- L is the inductor value
- V_{BAT} is the battery voltage

VCC is the input voltage

A reasonable starting point for setting inductor ripple current is $\triangle I_L = 0.3 \times I_{CH}$, I_{CH} is the charge current. Remember that the maximum $\triangle I_L$ occurs at the maximum input voltage and the lowest inductor value. So lower charge current generally calls for larger inductor value.

In the meantime, inductor value should meet the requirement of the following equation:

$$L > 5 X (VCC-VBAT)$$
 (uH)

MOSFET Selection

The CN3768 uses a P-channel power MOSFET switch. The MOSFET must be selected to meet the efficiency or power dissipation requirements of the charging circuit as well as the maximum temperature of the MOSFET. The peak-to-peak gate drive voltage is set internally, this voltage is typically 6V. Consequently, logic-level threshold MOSFETs must be used. Pay close attention to the BV_{DSS} specification for the MOSFET as well; many of the logic level MOSFETs are limited to 30V or less.

Selection criteria for the power MOSFET includes the "on" resistance Rds(on), total gate charge Qg, reverse transfer capacitance C_{RSS}, input voltage and maximum charge current.

The MOSFET power dissipation at maximum output current is approximated by the equation:

$$Pd = \frac{VBAT}{VCC} X Rds(on) X ICH2 X (1+0.005dT)$$

Where:

Pd is the power dissipation of the power MOSFET

VBAT is the maximum battery voltage

VCC is the minimum input voltage

Rds(on) is the power MOSFET's on resistance at room temperature

ICH is the charge current

dT is the temperature difference between actual ambient temperature and room temperature(25 °C) In addition to the I²Rds(on) loss, the power MOSFET still has transition loss, which are highest at the highest input voltage. Generally speaking, for VIN<20V, the I²Rds(on) loss may be dominant, so the MOSFET with lower Rds(on) should be selected for better efficiency; for VIN>20V, the transition loss may be dominant, so the MOSFET with lower C_{RSS} can provide better efficiency. C_{RSS} is usually specified in the MOSFET characteristics; if not, then C_{RSS} can be calculated using C_{RSS} = Q_{GD}/ Δ V_{DS}.

The MOSFETs such as AO4459, STM9435(or WT9435), AO3407A can be used. The part numbers listed above are for reference only, the users can select the right MOSFET based on their requirements.

Diode Selection

The diodes D1 and D2 in Figure 1 are schottky diode, the current rating of the diodes should be at least the charge current limit, the voltage rating of the diode should exceed the maximum expected input voltage. The diode that is much larger than that is sufficient can result in larger transition losses due to their larger junction capacitance.

Diode D1 in Figure 1 is used as block diode to prevent battery current from flowing back to VCC when input supply is absent. Without D1, CN3768 consumes about 52uA current from battery(V_{BAT} =12V), so diode D1 can be removed if the 51uA battery current is not a consideration.

Battery Current In Sleep Mode

In the typical application circuit shown in Figure 1, when input voltage is powered off or lower than battery voltage, CN3768 will enter sleep mode. In sleep mode, the battery current includes:

- (1) The current into BAT pin and CSP pin, which is about $8uA(V_{BAT}=12V)$.
- (2) The current from battery to VCC pin via diode D1, which is determined by D1's leakage current. If diode D1 is not used, then the current flowing to VCC pin via inductor and body diode of P-channel MOSFET is about 44uA(V_{BAT}=12V).
- (3) The current from battery to GND via diode D2, which is also determined by D2's leakage current.

Using PMOS transistor to realize reverse connection protection of input power supply and prevent battery current backflow

In a typical application, diode D1 in figure 1 is used to prevent battery current backflow. However, due to the conduction voltage drop of the diode, when the current flowing through is relatively large, the power consumption of the diode is relatively large. In order to solve this problem, in the circuit in Fig. 3, the PMOS transistor M2 is used instead of the diode D1, which can not only prevent the battery current from flowing back, but also realize the reverse connection protection function of the input power supply.

In general, the technical requirements of PMOS transistor M2 are: the Vds must be greater than the maximum input power supply voltage, the Vgs must be greater than the battery voltage, and the on resistance and maximum drain current Id meet the requirements of charging current. Resistance R3 is generally 22K ohm.

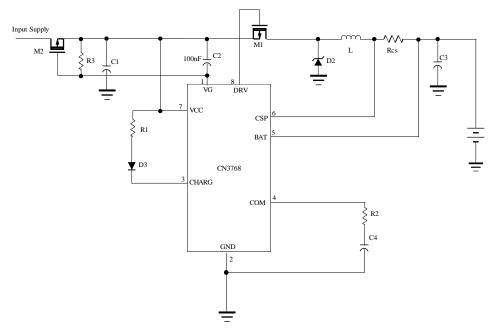


Figure 3 using PMOS to realize power reverse connection protection and

prevent battery current backflow

About the suppression of high frequency oscillation

In the case of high input voltage or large charging current, if the PCB layout and wiring are unreasonable, or the parasitic inductance of diode and p-channel FET is relatively large, high-frequency oscillation above 10MHz will be generated at the moment when p-channel FET is turned on or off. High frequency oscillation waveform can be observed on the positive pole of input power supply and the negative pole of diode D2 with oscilloscope. In order to suppress high-frequency radiation, in addition to improving PCB layout and wiring, high-frequency suppression circuits can also be added, such as R5 and C5 in Fig. 4.

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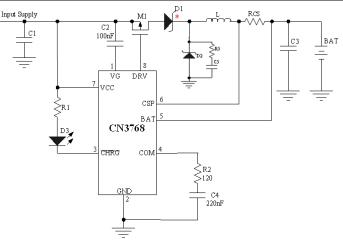


Figure 4 high frequency oscillation suppression

PCB Layout Considerations

When laying out the printed circuit board, the following considerations should be taken to ensure proper operation of the IC.

- (1) To minimize radiation, the 2 diodes, pass transistor, inductor and the input bypass capacitor traces should be kept as short as possible. The positive side of the input capacitor should be close to the source of the P-channel MOSFET; it provides the AC current to the pass transistor. The connection between the diode and the pass transistor should also be kept as short as possible.
- (2) The compensation capacitor connected at the COM pin should return to the ground pin of the IC. This will prevent ground noise from disrupting the loop stability.
- (3) Output capacitor ground and catch diode (D2 in Figure 1) ground connections need to feed into same copper that connects to the input capacitor ground before tying back into system ground.
- (4) Analog ground and power ground(or switching ground) should return to system ground separately.
- (5) The ground pins also works as a heat sink, therefore use a generous amount of copper around the ground pins. This is especially important for high VCC and/or high gate capacitance applications.
- (6) Place the charge current sense resistor R_{CS} right next to the inductor output but oriented such that the IC's CSP and BAT traces going to R_{CS} are not long. The 2 traces need to be routed together as a single pair on the same layer at any given time with smallest trace spacing possible.
- (7) The CSP and BAT pins should be connected directly to the 2 terminals of current sense resistor (Kelvin sensing) for best charge current accuracy. See Figure 5 as an example.

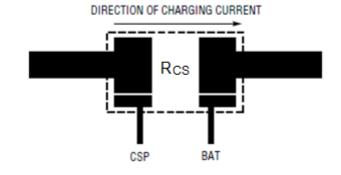
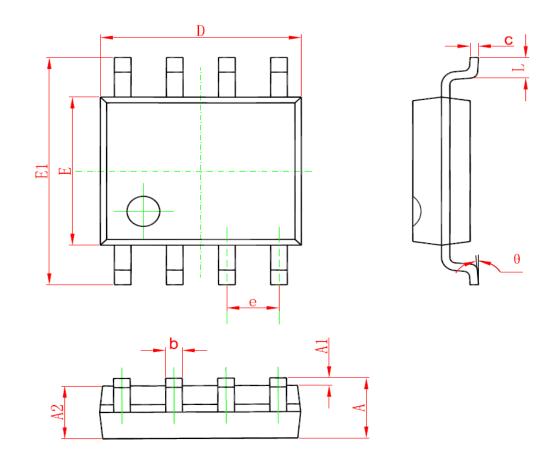


Figure 5 Kelvin Sensing of Charge Current

Package Information

SOP8 PACKAGE OUTLINE DIMENSIONS



Com La L	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1. 350	1. 750	0.053	0.069	
A1	0. 100	0. 250	0.004	0.010	
A2	1. 350	1. 550	0.053	<mark>0. 061</mark>	
b	0. 330	<mark>0. 510</mark>	0.013	0.020	
С	0. 170	0. 250	0.006	0.010	
D	4. 700	5.100	0. 185	0.200	
E	3. 800	4.000	0.150	0.157	
E1	5. <mark>80</mark> 0	6.200	0. 228	0.244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

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